

# Global Advanced Packaging for Automotive Chips Supply, Demand and Key Producers, 2023-2029

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## Abstracts

The global Advanced Packaging for Automotive Chips market size is expected to reach \$ 999 million by 2029, rising at a market growth of 11.2% CAGR during the forecast period (2023-2029).

Currently the key players of Automotive OSAT are Amkor, ASE Group and UTAC, Others Automotive OSAT players are mainly located in China Taiwan, South Korea, China mainland, Southeast Asia (Singapore and Malaysia), including Chipbond Technology Corporation, ChipMOS TECHNOLOGIES, Powertech Technology Inc. (PTI), King Yuan Electronics Corp. (KYECC), OSE CORP., Sigurd Microelectronics, Natronix Semiconductor Technology, Nepes, SFA Semicon, Unisem Group, Carsem, Union Semiconductor Hefei Co., Ltd., Tongfu Microelectronics (TFME), Hefei Chipmore Technology Co.,Ltd., JCET Group and HT-tech, etc.

Automotive electronics encompasses a variety of products – from body electronics and access systems to engine, lighting and infotainment components. This report studies the Advanced Packaging for Automotive Chips.

This report studies the global Advanced Packaging for Automotive Chips demand, key companies, and key regions.

This report is a detailed and comprehensive analysis of the world market for Advanced Packaging for Automotive Chips, and provides market size (US\$ million) and Year-over-Year (YoY) growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of Advanced Packaging for Automotive Chips that contribute to its increasing demand across many markets.

## Highlights and key features of the study

Global Advanced Packaging for Automotive Chips total market, 2018-2029, (USD Million)

Global Advanced Packaging for Automotive Chips total market by region & country, CAGR, 2018-2029, (USD Million)

U.S. VS China: Advanced Packaging for Automotive Chips total market, key domestic companies and share, (USD Million)

Global Advanced Packaging for Automotive Chips revenue by player and market share 2018-2023, (USD Million)

Global Advanced Packaging for Automotive Chips total market by Package Types, CAGR, 2018-2029, (USD Million)

Global Advanced Packaging for Automotive Chips total market by Application, CAGR, 2018-2029, (USD Million).

This reports profiles major players in the global Advanced Packaging for Automotive Chips market based on the following parameters – company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include NXP, Infineon (Cypress), Renesas, Texas Instrument, STMicroelectronics, Bosch, onsemi, Mitsubishi Electric and Rapidus, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Advanced Packaging for Automotive Chips market.

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), by player, by regions, by Package Types, and by Application. Data is given for the years 2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

## Global Advanced Packaging for Automotive Chips Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

## Global Advanced Packaging for Automotive Chips Market, Segmentation by Package Types

FC (Flip Chip)

WLCSP

Others

## Global Advanced Packaging for Automotive Chips Market, Segmentation by Application

Automotive OSAT

Automotive IDM

## Companies Profiled:

NXP

Infineon (Cypress)

Renesas

Texas Instrument

STMicroelectronics

Bosch

onsemi

Mitsubishi Electric

Rapidus

Rohm

ADI

Microchip (Microsemi)

Amkor

ASE (SPIL)

UTAC

JCET (STATS ChipPAC)

Carsem

King Yuan Electronics Corp. (KYEC)

KINGPAK Technology Inc

Powertech Technology Inc. (PTI)

SFA Semicon

Unisem Group

Chipbond Technology Corporation

ChipMOS TECHNOLOGIES

OSE CORP.

Sigurd Microelectronics

Natronix Semiconductor Technology

Nepes

KESM Industries Berhad

Forehope Electronic (Ningbo) Co.,Ltd.

Union Semiconductor?Hefei?Co., Ltd.

Tongfu Microelectronics (TFME)

Hefei Chipmore Technology Co.,Ltd.

HT-tech

China Wafer Level CSP Co., Ltd

Ningbo ChipEx Semiconductor Co., Ltd

Guangdong Leadyo IC Testing

Unimos Microelectronics (Shanghai)

Sino Technology

## Taiji Semiconductor (Suzhou)

### Key Questions Answered

1. How big is the global Advanced Packaging for Automotive Chips market?
2. What is the demand of the global Advanced Packaging for Automotive Chips market?
3. What is the year over year growth of the global Advanced Packaging for Automotive Chips market?
4. What is the total value of the global Advanced Packaging for Automotive Chips market?
5. Who are the major players in the global Advanced Packaging for Automotive Chips market?

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Figure 32. WLCSP

Figure 33. Others

Figure 34. World Advanced Packaging for Automotive Chips Market Size Market Share by Package Types (2018-2029)

Figure 35. World Advanced Packaging for Automotive Chips Market Size by Application, (USD Million), 2018 & 2022 & 2029

Figure 36. World Advanced Packaging for Automotive Chips Market Size Market Share by Application in 2022

Figure 37. Automotive OSAT

Figure 38. Automotive IDM

Figure 39. Advanced Packaging for Automotive Chips Industrial Chain

Figure 40. Methodology

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